

φ0.10 Micro-Hole Drilling Performance

φ0.10 ドリル 加工事例

用途:半導体パッケージ用、ビルドアップ用内層コア材 等 FBGA、BGA、for HDI etc...

Drilling Condition 加工条件

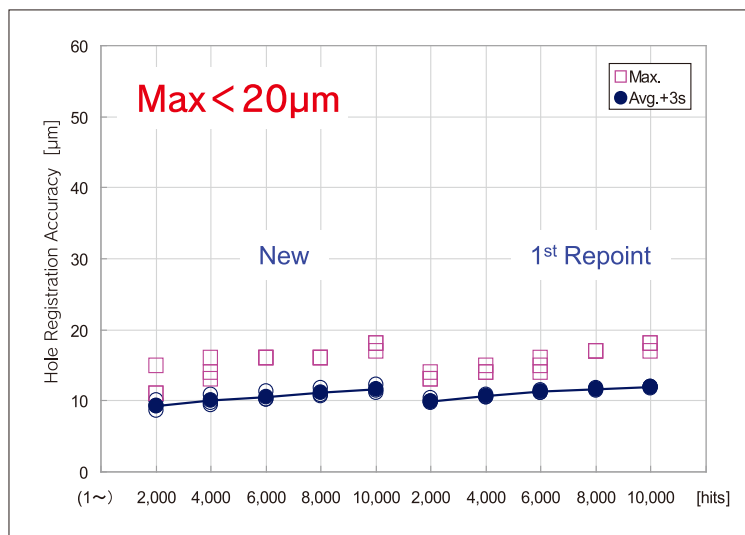
Work Material : BT CCL-HL832NX t0.1(Double Sided) x 8 stack height 6/6μmCopper

S : 350,000 min⁻¹ F : 2.8 m/min f : 8 μm/rev

Set Life : 10,000 hits x Reprint 1 time = Total 20,000 hits

Hole Registration Accuracy 穴位置精度

Hole Wall Quality at 10,000th hit 内壁粗さ

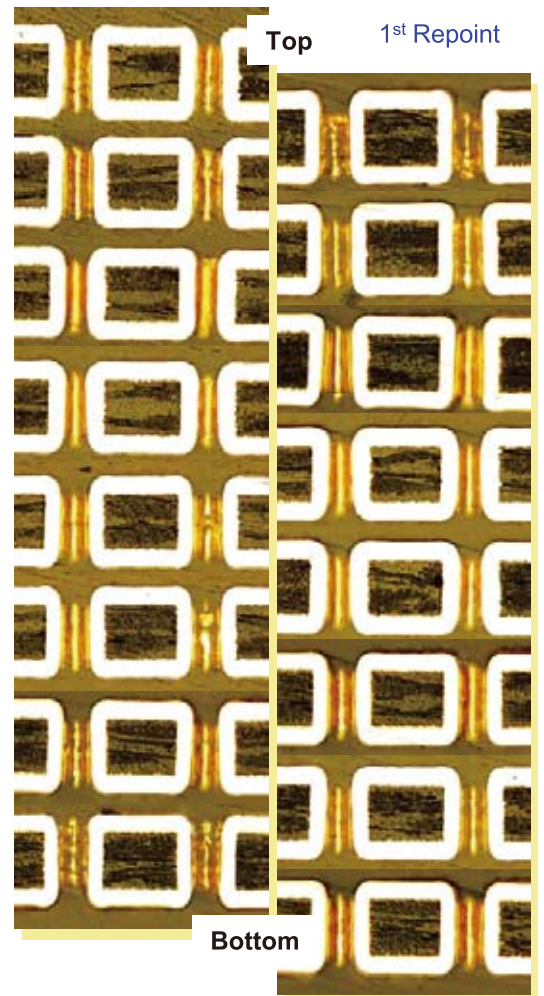


Max < 6μm

New

Top

1st Reprint



Bottom

Succeed in higher stack height of Halogen free material
ハロゲンフリー基材加工で重ね枚数UPを実現

Drilling efficiency 115%
加工効率115%

Hole registration accuracy
Max 10μm improvement
穴位置Max10μm改善

'08JPCA展示データ

Work Material : MCL-E-679FG(R)

t0.1(Double Sided) x 7 stack height (4/4μmCopper)

Set Life : 10,000 hits x Reprint 1 time = Total 20,000 hits

Hole Registration Accuracy : Max < 30μm

Hole Wall Quality at 10,000hits : Max < 5μm